Renesas Electronics America Inc - R5F213N7TNBX#W5 Datasheet

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	43
Program Memory Size	48KB (48K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-WFBGA
Supplier Device Package	48-WPP (3.05x3.05)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f213n7tnbx-w5

1.4 Pin Assignment

Figure 1.3 shows Pin Assignment. Table 1.4 outlines the Pin Name Information by Pin Number.

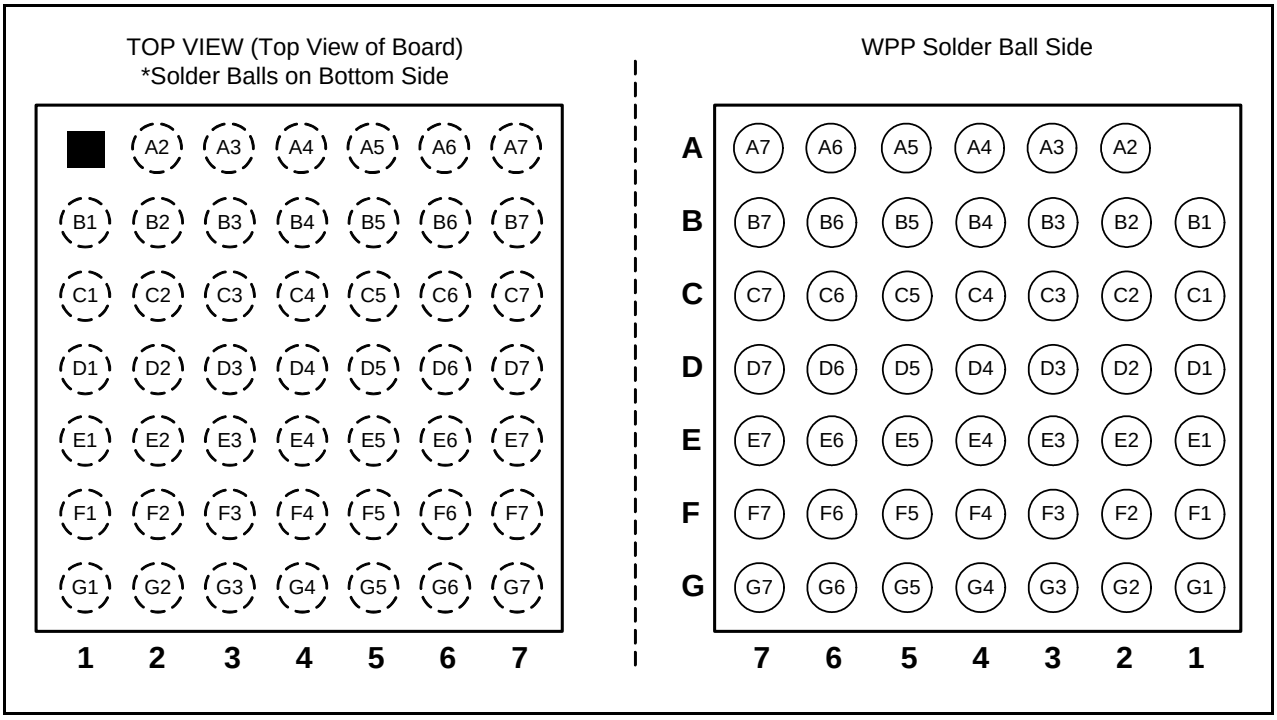


Figure 1.3 Pin Assignment

Pin Number		Pin Name
A	1	—
	2	VREF/P4_2
	3	P4_4(/XCOUT)
	4	VSS/AVSS
	5	P4_6/XIN
	6	VCC/AVCC
	7	P3_5(/TRCIOD/CLK2)/SSCK_0/SCL_0
B	1	P6_3(/TXD1)/SSCK_3/SCL_3
	2	P6_1/$\overline{\text{SCS\_3}}$
	3	P3_0(/TRAO/$\overline{\text{INT3}}$)
	4	P4_3(/XCIN)
	5	P4_7/XOUT
	6	P3_7(/RXD2/TXD2)/TRAO/SSO_0/SDA_0
	7	P3_4(/TRCIOC/RXD2/TXD2)/SSI_0
C	1	P0_0/AN7(/TRCIOA/TRCTRG)/CHxC
	2	P6_4(/RXD1)/SSO_3/SDA_3
	3	P6_2(/CLK1)/SSI_3
	4	MODE
	5	$\overline{\text{RESET}}$
	6	P3_3/$\overline{\text{INT3}}$(/TRCCLK/$\overline{\text{CTS2}}$/$\overline{\text{RTS2}}$)/$\overline{\text{SCS\_0}}$
	7	P2_7/$\overline{\text{SCS\_2}}$
D	1	P0_2/AN5/RXD1(/TRCIOA/TRCTRG)/CHxA
	2	P0_1/AN6(/TXD1/TRCIOA/TRCTRG)/CHxB
	3	P6_0(/TREO/$\overline{\text{INT2}}$)
	4	P1_4(/TXD0/TRCCLK)

Pin Number		Pin Name
D	5	P2_6
	6	P2_5/SSO_1/SDA_1
	7	P2_4/SSCK_1/SCL_1
E	1	P0_3/AN4(/CLK1/TRCIOB)/CH0
	2	P0_4/AN3/TREO(/TRCIOB)/CH1
	3	P1_0/$\overline{\text{KI0}}$/AN8(/TRCIOD)
	4	P1_5(/RXD0/TRAIO/$\overline{\text{INT1}}$)
	5	P2_1(/TRCIOC)
	6	P2_3/SSI_1
	7	P2_2(/TRCIOD)/$\overline{\text{SCS\_1}}$
F	1	P0_5/AN2(/TRCIOB)/CH2
	2	P0_6/AN1(/TRCIOD)/CH3
	3	P1_2/$\overline{\text{KI2}}$/AN10(/TRCIOB)
	4	P1_7/$\overline{\text{INT1}}$(/TRAIO)
	5	P6_5/$\overline{\text{INT4}}$(/CLK2/CLK1/TRCIOB)/SSI_2
	6	P6_7(/$\overline{\text{INT3}}$/TRCIOD)/SSO_2/SDA_2
	7	P2_0(/$\overline{\text{INT1}}$/TRCIOB)
G	1	P0_7/AN0(/TRCIOC)/CH4
	2	P1_1/$\overline{\text{KI1}}$/AN9(/TRCIOA/TRCTRG)
	3	P1_3/$\overline{\text{KI3}}$/AN11/TRBO(/TRCIOC)
	4	P1_6(/CLK0)/$\overline{\text{INT2}}$
	5	P4_5/$\overline{\text{INT0}}$(/RXD2)/ADTRG
	6	P6_6/$\overline{\text{INT2}}$(/TXD2/TRCIOC)/SSCK_2/SCL_2
	7	P3_1(/TRBO)

Table 1.6 Pin Functions (2)

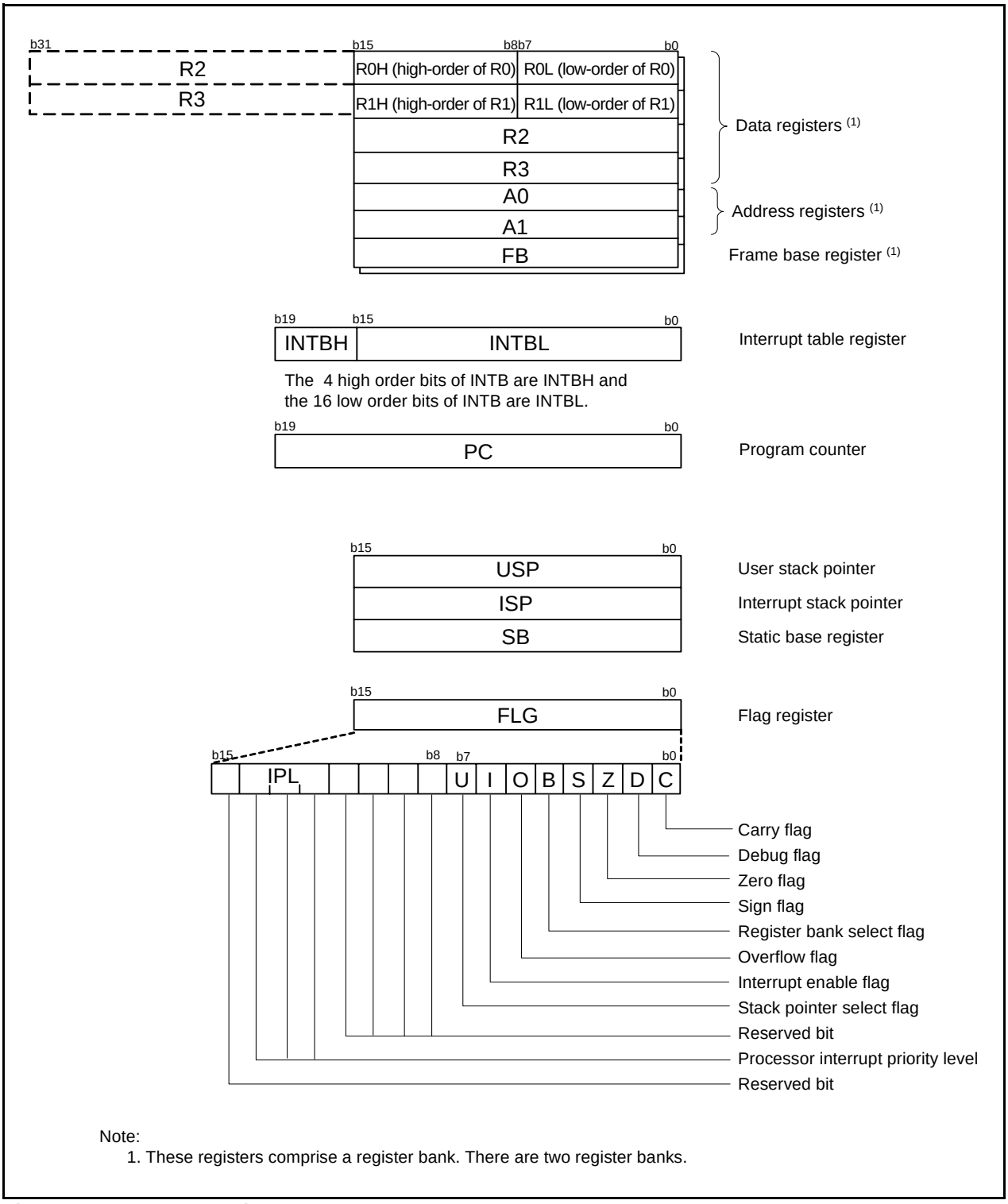
Item	Pin Name	I/O Type	Description
SSU	SSI_i	I/O	Data I/O pin.
	$\overline{\text{SCS\_i}}$	I/O	Chip-select signal I/O pin.
	SSCK_i	I/O	Clock I/O pin.
	SSO_i	I/O	Data I/O pin.
I^2C bus	SCL_i	I/O	Clock I/O pin
	SDA_i	I/O	Data I/O pin
Reference voltage input	VREF	I	Reference voltage input pin to A/D converter.
A/D converter	AN0 to AN11	I	Analog input pins to A/D converter.
	$\overline{\text{ADTRG}}$	I	AD external trigger input pin.
Sensor control unit	CHxA, CHxB, CHxC	I/O	Control pins for electrostatic capacitive touch detection
	CH0 to CH4	I	Electrostatic capacitive touch detection pins
I/O port	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_1, P3_3 to P3_5, P3_7, P4_3 to P4_7, P6_0 to P6_7	I/O	CMOS I/O ports. Each port has an I/O select direction register, allowing each pin in the port to be directed for input or output individually. Any port set to input can be set to use a pull-up resistor or not by a program.
Input port	P4_2	I	Input-only port.

i = 0 to 3

I: Input O: Output I/O: Input and output

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU contains 13 registers. R0, R1, R2, R3, A0, A1, and FB configure a register bank. There are two sets of register bank.



Note:
1. These registers comprise a register bank. There are two register banks.

Figure 2.1 CPU Registers

2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3. R0 can be split into high-order bits (R0H) and low-order bits (R0L) to be used separately as 8-bit data registers. R1H and R1L are analogous to R0H and R0L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic, and logic operations. A1 is analogous to A0. A1 can be combined with A0 and as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the starting address of an interrupt vector table.

2.5 Program Counter (PC)

PC is 20 bits wide and indicates the address of the next instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP and ISP, are each 16 bits wide. The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is an 11-bit register indicating the CPU state.

2.8.1 Carry Flag (C)

The C flag retains carry, borrow, or shift-out bits that have been generated by the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debugging only. Set it to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0; otherwise to 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value; otherwise to 0.

2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is set to 1.

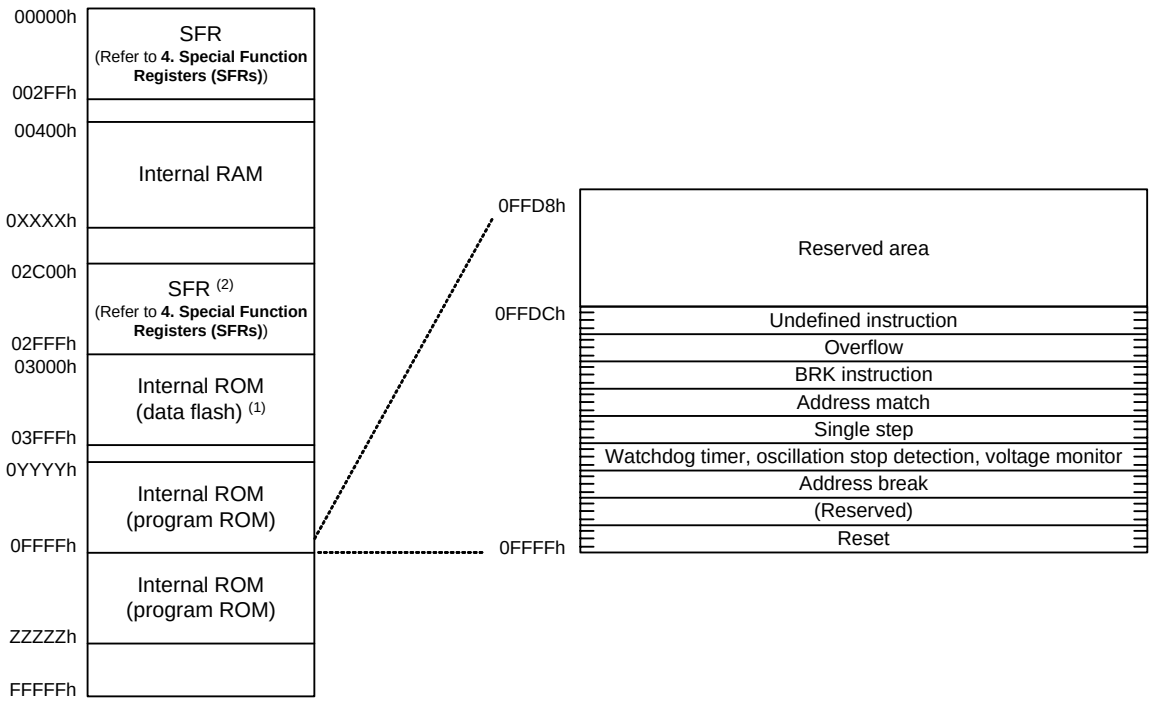
2.8.6 Overflow Flag (O)

The O flag is set to 1 when an operation results in an overflow; otherwise to 0.

3. Memory

3.1 R8C/3NT Group

Figure 3.1 is a Memory Map of R8C/3NT Group. The R8C/3NT Group has a 1-Mbyte address space from addresses 00000h to FFFFFh. The internal ROM (program ROM) is allocated lower addresses, beginning with address 0FFFFh. For example, a 64-Kbyte internal ROM area is allocated addresses 04000h to 13FFFh.
The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. The starting address of each interrupt routine is stored here.
The internal ROM (data flash) is allocated addresses 03000h to 03FFFh.
The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 6-Kbyte internal RAM area is allocated addresses 00400h to 01BFFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.
Special function registers (SFRs) are allocated addresses 00000h to 002FFh and 02C00h to 02FFFh (the SFR areas for the DTC and other modules). Peripheral function control registers are allocated here. All unallocated spaces within the SFRs are reserved and cannot be accessed by users.



Notes:
1. The data flash indicates block A (1 Kbyte), block B (1 Kbyte), block C (1 Kbyte), and block D (1 Kbyte).
2. The SFR areas for the DTC and other modules are allocated to addresses 02C00h to 02FFFh.
3. The blank areas are reserved and cannot be accessed by users.

Part Number	Internal ROM			Internal RAM	
	Size	Address 0YYYYh	Address ZZZZZh	Size	Address 0XXXXh
R5F213N7TNBX	48 Kbytes	04000h	–	4 Kbytes	013FFh
R5F213N8TNBX	64 Kbytes	04000h	13FFFh	6 Kbytes	01BFFh
R5F213NATNBX	96 Kbytes	04000h	1BFFFh	8 Kbytes	023FFh
R5F213NCTNBX	128 Kbytes	04000h	23FFFh	10 Kbytes	02BFFh

Figure 3.1 Memory Map of R8C/3NT Group

Table 4.4 SFR Information (4) (1)

Address	Register	Symbol	After Reset
00C0h	A/D Register 0	AD0	XXh
00C1h			000000XXb
00C2h	A/D Register 1	AD1	XXh
00C3h			000000XXb
00C4h	A/D Register 2	AD2	XXh
00C5h			000000XXb
00C6h	A/D Register 3	AD3	XXh
00C7h			000000XXb
00C8h	A/D Register 4	AD4	XXh
00C9h			000000XXb
00CAh	A/D Register 5	AD5	XXh
00CBh			000000XXb
00CCh	A/D Register 6	AD6	XXh
00CDh			000000XXb
00CEh	A/D Register 7	AD7	XXh
00CFh			000000XXb
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Mode Register	ADMOD	00h
00D5h	A/D Input Select Register	ADINSEL	11000000b
00D6h	A/D Control Register 0	ADCON0	00h
00D7h	A/D Control Register 1	ADCON1	00h
00D8h			
00D9h			
00DAh			
00DBh			
00DCh			
00DDh			
00DEh			
00DFh			
00E0h	Port P0 Register	P0	XXh
00E1h	Port P1 Register	P1	XXh
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h	Port P2 Register	P2	XXh
00E5h	Port P3 Register	P3	XXh
00E6h	Port P2 Direction Register	PD2	00h
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h			
00EAh	Port P4 Direction Register	PD4	00h
00EBh			
00ECh	Port P6 Register	P6	XXh
00EDh			
00EEh	Port P6 Direction Register	PD6	00h
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h			
00F5h			
00F6h			
00F7h			
00F8h			
00F9h			
00FAh			
00FBh			
00FCh			
00FDh			
00FEh			
00FFh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.5 SFR Information (5) (1)

Address	Register	Symbol	After Reset
0100h	Timer RA Control Register	TRACR	00h
0101h	Timer RA I/O Control Register	TRAIOC	00h
0102h	Timer RA Mode Register	TRAMR	00h
0103h	Timer RA Prescaler Register	TRAPRE	FFh
0104h	Timer RA Register	TRA	FFh
0105h			
0106h			
0107h			
0108h	Timer RB Control Register	TRBCR	00h
0109h	Timer RB One-Shot Control Register	TRBOCR	00h
010Ah	Timer RB I/O Control Register	TRBIOC	00h
010Bh	Timer RB Mode Register	TRBMR	00h
010Ch	Timer RB Prescaler Register	TRBPRE	FFh
010Dh	Timer RB Secondary Register	TRBSC	FFh
010Eh	Timer RB Primary Register	TRBPR	FFh
010Fh			
0110h			
0111h			
0112h			
0113h			
0114h			
0115h			
0116h			
0117h			
0118h	Timer RE Second Data Register / Counter Data Register	TRESEC	00h
0119h	Timer RE Minute Data Register / Compare Data Register	TREMIN	00h
011Ah	Timer RE Hour Data Register	TREHR	00h
011Bh	Timer RE Day of Week Data Register	TREWK	00h
011Ch	Timer RE Control Register 1	TRECR1	00h
011Dh	Timer RE Control Register 2	TRECR2	00h
011Eh	Timer RE Count Source Select Register	TRECSR	00001000b
011Fh			
0120h	Timer RC Mode Register	TRCMR	01001000b
0121h	Timer RC Control Register 1	TRCCR1	00h
0122h	Timer RC Interrupt Enable Register	TRCIER	01110000b
0123h	Timer RC Status Register	TRCSR	01110000b
0124h	Timer RC I/O Control Register 0	TRCIOR0	10001000b
0125h	Timer RC I/O Control Register 1	TRCIOR1	10001000b
0126h	Timer RC Counter	TRC	00h
0127h			00h
0128h	Timer RC General Register A	TRCGRA	FFh
0129h			FFh
012Ah	Timer RC General Register B	TRCGRB	FFh
012Bh			FFh
012Ch	Timer RC General Register C	TRCGRC	FFh
012Dh			FFh
012Eh	Timer RC General Register D	TRCGRD	FFh
012Fh			FFh
0130h	Timer RC Control Register 2	TRCCR2	00011000b
0131h	Timer RC Digital Filter Function Select Register	TRCDF	00h
0132h	Timer RC Output Master Enable Register	TRCOER	01111111b
0133h	Timer RC Trigger Control Register	TRCADCR	00h
0134h			
0135h			
0136h			
0137h			
0138h			
0139h			
013Ah			
013Bh			
013Ch			
013Dh			
013Eh			
013Fh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.7 SFR Information (7) (1)

Address	Register	Symbol	After Reset
0180h	Timer RA Pin Select Register	TRASR	00h
0181h	Timer RB/RC Pin Select Register	TRBRCSR	00h
0182h	Timer RC Pin Select Register 0	TRCPSR0	00h
0183h	Timer RC Pin Select Register 1	TRCPSR1	00h
0184h			
0185h			
0186h	Timer Pin Select Register	TIMSR	00h
0187h			
0188h	UART0 Pin Select Register	U0SR	00h
0189h	UART1 Pin Select Register	U1SR	00h
018Ah	UART2 Pin Select Register 0	U2SR0	00h
018Bh	UART2 Pin Select Register 1	U2SR1	00h
018Ch	SSU/IIC Pin Select Register	SSUIICSR	00h
018Dh	Low-Voltage Signal Mode Control Register 1	LVMR1	00h
018Eh	INT Interrupt Input Pin Select Register	INTSR	00h
018Fh	I/O Function Pin Select Register	PINSR	00h
0190h	Low-Voltage Signal Mode Control Register	LVMR	00h
0191h	I/O Function Pin Select Register 1	PINSR1	00h
0192h	I/O Function Pin Select Register 2	PINSR2	00h
0193h	SS0 Bit Counter Register	SS0BR	F8h
0194h	SS0 Transmit Data Register L / IIC_0 bus Transmit Data Register (2)	SS0TDR / IC0DRT	FFh
0195h	SS0 Transmit Data Register H (2)	SS0TDRH	FFh
0196h	SS0 Receive Data Register L / IIC_0 bus Receive Data Register (2)	SS0RDR / IC0DRR	FFh
0197h	SS0 Receive Data Register H (2)	SS0RDRH	FFh
0198h	SS0 Control Register H / IIC_0 bus Control Register 1 (2)	SS0CRH / IC0CR1	00h
0199h	SS0 Control Register L / IIC_0 bus Control Register 2 (2)	SS0CRL / IC0CR2	01111101b
019Ah	SS0 Mode Register / IIC_0 bus Mode Register (2)	SS0MR / IC0MR	00010000b / 00011000b
019Bh	SS0 Enable Register / IIC_0 bus Interrupt Enable Register (2)	SS0ER / IC0IER	00h
019Ch	SS0 Status Register / IIC_0 bus Status Register (2)	SS0SR / IC0SR	00h / 0000X000b
019Dh	SS0 Mode Register 2 / Slave Address Register (2)	SS0MR2 / SAR	00h
019Eh			
019Fh			
01A0h			
01A1h			
01A2h			
01A3h			
01A4h			
01A5h			
01A6h			
01A7h			
01A8h			
01A9h			
01AAh			
01ABh			
01ACh			
01ADh			
01AEh			
01AFh			
01B0h			
01B1h			
01B2h	Flash Memory Status Register	FST	10000X00b
01B3h			
01B4h	Flash Memory Control Register 0	FMR0	00h
01B5h	Flash Memory Control Register 1	FMR1	00h
01B6h	Flash Memory Control Register 2	FMR2	00h
01B7h			
01B8h			
01B9h			
01BAh			
01BBh			
01BCh			
01BDh			
01BEh			
01BFh			

X: Undefined

Notes:

1. The blank areas are reserved and cannot be accessed by users.
2. Selectable by the IIC0SEL bit in the SSUIICSR register.

Table 4.9 SFR Information (9) (1)

Address	Register	Symbol	After Reset
0200h			
0201h			
0202h			
0203h			
0204h			
0205h			
0206h			
0207h			
0208h			
0209h			
020Ah			
020Bh			
020Ch			
020Dh			
020Eh			
020Fh			
0210h			
0211h			
0212h			
0213h	SS1 Bit Counter Register	SS1BR	F8h
0214h	SS1 Transmit Data Register L / IIC_1 bus Transmit Data Register (2)	SS1TDR/IC1DRT	FFh
0215h	SS1 Transmit Data Register H (2)	SS1TDRH	FFh
0216h	SS1 Receive Data Register L / IIC_1 bus Receive Data Register (2)	SS1RDR/IC1DRR	FFh
0217h	SS1 Receive Data Register H (2)	SS1RDRH	FFh
0218h	SS1 Control Register H / IIC_1 bus Control Register 1 (2)	SS1CRH/IC1CR1	00h
0219h	SS1 Control Register L / IIC_1 bus Control Register 2 (2)	SS1CRL/IC1CR2	01111101b
021Ah	SS1 Mode Register / IIC1 bus Mode Register (2)	SS1MR/IC1MR	00010000b/00011000b
021Bh	SS1 Enable Register / IIC_1 bus Interrupt Enable Register (2)	SS1ER/IC1IER	00h
021Ch	SS1 Status Register / IIC_1 bus Status Register (2)	SS1SR/IC1SR	00h/0000X000b
021Dh	SS1 Mode Register 2 / Slave Address Register (2)	SS1MR2/SAR1	00h
021Eh			
021Fh			
0220h			
0221h			
0222h			
0223h			
0224h			
0225h			
0226h			
0227h			
0228h			
0229h			
022Ah			
022Bh			
022Ch			
022Dh			
022Eh			
022Fh			
0230h			
0231h			
0232h			
0233h	SS2 Bit Counter Register	SS2BR	F8h
0234h	SS2 Transmit Data Register L / IIC_2 bus Transmit Data Register (3)	SS2TDR/IC2DRT	FFh
0235h	SS2 Transmit Data Register H (3)	SS2TDRH	FFh
0236h	SS2 Receive Data Register L / IIC_2 bus Receive Data Register (3)	SS2RDR/IC2DRR	FFh
0237h	SS2 Receive Data Register H (3)	SS2RDRH	FFh
0238h	SS2 Control Register H / IIC_2 bus Control Register 1 (3)	SS2CRH/IC2CR1	00h
0239h	SS2 Control Register L / IIC_2 bus Control Register 2 (3)	SS2CRL/IC2CR2	01111101b
023Ah	SS2 Mode Register / IIC_2 bus Mode Register (3)	SS2MR/IC2MR	00010000b/00011000b
023Bh	SS2 Enable Register / IIC_2 bus Interrupt Enable Register (3)	SS2ER/IC2IER	00h
023Ch	SS2 Status Register / IIC_2 bus Status Register (3)	SS2SR/IC2SR	00h/0000X000b
023Dh	SS2 Mode Register 2 / Slave Address Register (3)	SS2MR2/SAR2	00h
023Eh			
023Fh			

X: Undefined

Notes:

1. The blank areas are reserved and cannot be accessed by users.
2. Selectable by the IIC1SEL bit in the SSUIICSR register.
3. Selectable by the IIC2SEL bit in the SSUIICSR register.

Table 4.15 ID Code Areas and Option Function Select Area

Address	Area Name	Symbol	After Reset
:			
FFDBh	Option Function Select Register 2	OFS2	(Note 1)
:			
FFDFh	ID1		(Note 2)
:			
FFE3h	ID2		(Note 2)
:			
FFEBh	ID3		(Note 2)
:			
FFEFh	ID4		(Note 2)
:			
FFF3h	ID5		(Note 2)
:			
FFF7h	ID6		(Note 2)
:			
FFFBh	ID7		(Note 2)
:			
FFFFh	Option Function Select Register	OFS	(Note 1)

Notes:

1. The option function select area is allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program.
   Do not write additions to the option function select area. If the block including the option function select area is erased, the option function select area is set to FFh.
   When blank products are shipped, the option function select area is set to FFh. It is set to the written value after written by the user.
   When factory-programming products are shipped, the value of the option function select area is the value programmed by the user.
2. The ID code areas are allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program.
   Do not write additions to the ID code areas. If the block including the ID code areas is erased, the ID code areas are set to FFh.
   When blank products are shipped, the ID code areas are set to FFh. They are set to the written value after written by the user.
   When factory-programming products are shipped, the value of the ID code areas is the value programmed by the user.

5. Electrical Characteristics

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated Value	Unit
V_{CC}/AV_{CC}	Supply voltage		–0.3 to 6.5	V
V_I	Input voltage		–0.3 to V_{CC} + 0.3	V
V_O	Output voltage		–0.3 to V_{CC} + 0.3	V
P_d	Power dissipation	$-20°C \leq T_{opr} \leq 85°C$	500	mW
T_{opr}	Operating ambient temperature		–20 to 85 (N version)	°C
T_{stg}	Storage temperature		–65 to 150	°C

Table 5.2 Recommended Operating Conditions (1)

Symbol	Parameter				Conditions	Standard			Unit
						Min.	Typ.	Max.	
V_{CC}/AV_{CC}	Supply voltage					1.8	—	5.5	V
V_{SS}/AV_{SS}	Supply voltage					—	0	—	V
V_{IH}	Input “H” voltage	Other than CMOS input				0.8 V_{CC}	—	V_{CC}	V
		CMOS input	Input level switching function (I/O port)	Input level selection: 0.35 V_{CC}	4.0 V ≤ V_{CC} ≤ 5.5 V	0.5 V_{CC}	—	V_{CC}	V
					2.7 V ≤ V_{CC} < 4.0 V	0.55 V_{CC}	—	V_{CC}	V
					1.8 V ≤ V_{CC} < 2.7 V	0.65 V_{CC}	—	V_{CC}	V
				Input level selection: 0.5 V_{CC}	4.0 V ≤ V_{CC} ≤ 5.5 V	0.65 V_{CC}	—	V_{CC}	V
					2.7 V ≤ V_{CC} < 4.0 V	0.7 V_{CC}	—	V_{CC}	V
					1.8 V ≤ V_{CC} < 2.7 V	0.8 V_{CC}	—	V_{CC}	V
				Input level selection: 0.7 V_{CC}	4.0 V ≤ V_{CC} ≤ 5.5 V	0.85 V_{CC}	—	V_{CC}	V
					2.7 V ≤ V_{CC} < 4.0 V	0.85 V_{CC}	—	V_{CC}	V
					1.8 V ≤ V_{CC} < 2.7 V	0.85 V_{CC}	—	V_{CC}	V
		External clock input (XOUT)				1.2	—	V_{CC}	V
V_{IL}	Input “L” voltage	Other than CMOS input				0	—	0.2 V_{CC}	V
		CMOS input	Input level switching function (I/O port)	Input level selection: 0.35 V_{CC}	4.0 V ≤ V_{CC} ≤ 5.5 V	0	—	0.2 V_{CC}	V
					2.7 V ≤ V_{CC} < 4.0 V	0	—	0.2 V_{CC}	V
					1.8 V ≤ V_{CC} < 2.7 V	0	—	0.2 V_{CC}	V
				Input level selection: 0.5 V_{CC}	4.0 V ≤ V_{CC} ≤ 5.5 V	0	—	0.4 V_{CC}	V
					2.7 V ≤ V_{CC} < 4.0 V	0	—	0.3 V_{CC}	V
					1.8 V ≤ V_{CC} < 2.7 V	0	—	0.2 V_{CC}	V
				Input level selection: 0.7 V_{CC}	4.0 V ≤ V_{CC} ≤ 5.5 V	0	—	0.55 V_{CC}	V
					2.7 V ≤ V_{CC} < 4.0 V	0	—	0.45 V_{CC}	V
					1.8 V ≤ V_{CC} < 2.7 V	0	—	0.35 V_{CC}	V
		External clock input (XOUT)				0	—	0.4	V
$I_{OH(sum)}$	Peak sum output “H” current		Sum of all pins $I_{OH(peak)}$			—	—	–160	mA
$I_{OH(sum)}$	Average sum output “H” current		Sum of all pins $I_{OH(avg)}$			—	—	–80	mA
$I_{OH(peak)}$	Peak output “H” current		Drive capacity Low			—	—	–10	mA
			Drive capacity High			—	—	–40	mA
$I_{OH(avg)}$	Average output “H” current		Drive capacity Low			—	—	–5	mA
			Drive capacity High			—	—	–20	mA
$I_{OL(sum)}$	Peak sum output “L” current		Sum of all pins $I_{OL(peak)}$			—	—	160	mA
$I_{OL(sum)}$	Average sum output “L” current		Sum of all pins $I_{OL(avg)}$			—	—	80	mA
$I_{OL(peak)}$	Peak output “L” current		Drive capacity Low			—	—	10	mA
			Drive capacity High			—	—	40	mA
$I_{OL(avg)}$	Average output “L” current		Drive capacity Low			—	—	5	mA
			Drive capacity High			—	—	20	mA
$f_{(XIN)}$	XIN clock input oscillation frequency				2.7 V ≤ V_{CC} ≤ 5.5 V	—	—	20	MHz
					1.8 V ≤ V_{CC} < 2.7 V	—	—	5	MHz
$f_{(XCIN)}$	XCIN clock input oscillation frequency				1.8 V ≤ V_{CC} ≤ 5.5 V	—	32.768	50	kHz
fOCO40M	When used as the count source for timer RC (3)				2.7 V ≤ V_{CC} ≤ 5.5 V	32	—	40	MHz
fOCO-F	fOCO-F frequency				2.7 V ≤ V_{CC} ≤ 5.5 V	—	—	20	MHz
					1.8 V ≤ V_{CC} < 2.7 V	—	—	5	MHz
—	System clock frequency				2.7 V ≤ V_{CC} ≤ 5.5 V	—	—	20	MHz
					1.8 V ≤ V_{CC} < 2.7 V	—	—	5	MHz
$f_{(BCLK)}$	CPU clock frequency				2.7 V ≤ V_{CC} ≤ 5.5 V	—	—	20	MHz
					1.8 V ≤ V_{CC} < 2.7 V	—	—	5	MHz

Notes:
1. V_{CC} = 1.8 to 5.5 V and T_{opr} = –20 to 85 °C (N version), unless otherwise specified.
2. The average output current indicates the average value of current measured during 100 ms.
3. fOCO40M can be used as the count source for timer RC in the range of V_{CC} = 2.7 to 5.5 V.

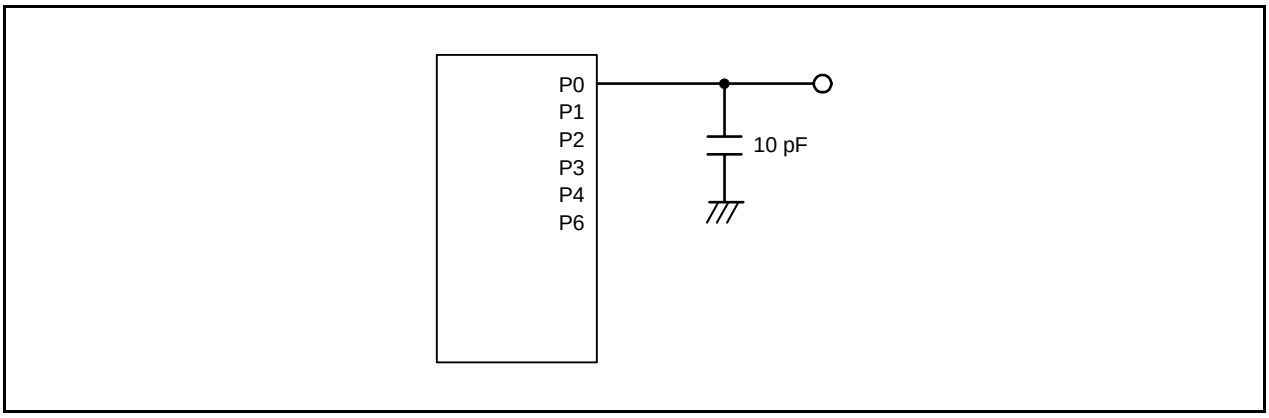


Figure 5.1 Ports P0 to P4, P6 Timing Measurement Circuit

Table 5.5 Flash Memory (Data flash Block A to Block D) Electrical Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance (2)		10,000 (3)	—	—	times
—	Byte program time (program/erase endurance ≤ 1,000 times)		—	160	TBD	µs
—	Byte program time (program/erase endurance > 1,000 times)		—	300	TBD	µs
—	Block erase time (program/erase endurance ≤ 1,000 times)		—	0.2	1	s
—	Block erase time (program/erase endurance > 1,000 times)		—	0.3	1	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		—	—	5 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	µs
—	Time from suspend until erase restart		—	—	30 + CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly stopped until reading is enabled		–	–	30 + CPU clock × 1 cycle	µs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		–20	—	85	°C
—	Data hold time (7)	Ambient temperature = 55 °C	20	—	—	year

Notes:
1. V_{CC} = 2.7 to 5.5 V and T_{opr} = –20 to 85 °C (N version), unless otherwise specified.
2. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one. However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed.)
4. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. In addition, averaging the erasure endurance between blocks A to D can further reduce the actual erasure endurance. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
5. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
6. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
7. The data hold time includes time that the power supply is off or the clock is not supplied.

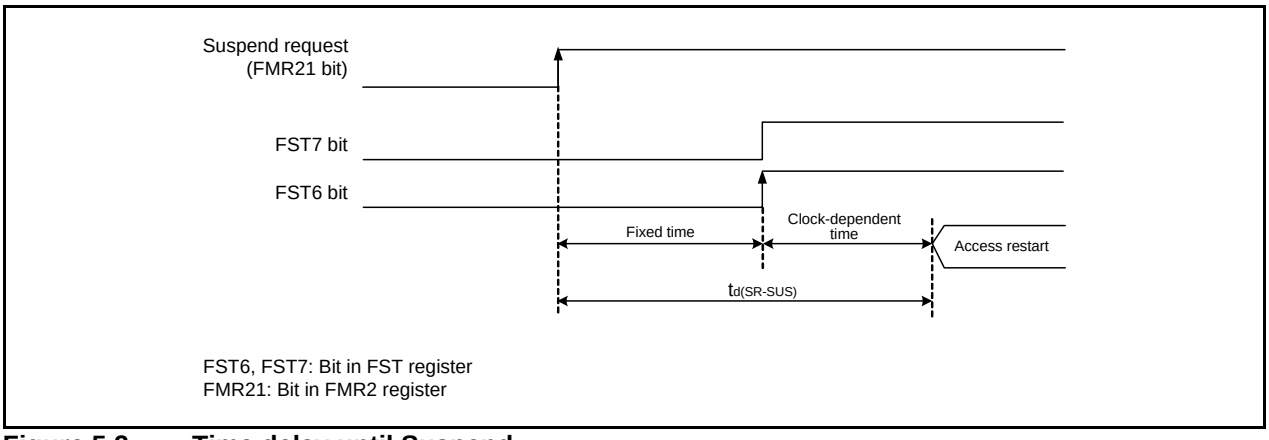


Figure 5.2 Time delay until Suspend

Table 5.10 High-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
—	High-speed on-chip oscillator frequency after reset	V_{CC} = 5.0 V, T_{opr} = 25 °C	—	40	—	MHz
	High-speed on-chip oscillator frequency when the FRA4 register correction value is written into the FRA1 register and the FRA5 register correction value into the FRA3 register (2)	V_{CC} = 5.0 V, T_{opr} = 25 °C	—	36.864	—	MHz
	High-speed on-chip oscillator frequency when the FRA6 register correction value is written into the FRA1 register and the FRA7 register correction value into the FRA3 register	V_{CC} = 5.0 V, T_{opr} = 25 °C	—	32	—	MHz
—	Oscillation stability time	V_{CC} = 5.0 V, T_{opr} = 25 °C	—	TBD	—	ms
—	Self power consumption at oscillation	V_{CC} = 5.0 V, T_{opr} = 25 °C	—	400	—	µA

Notes:
1. V_{CC} = 5.0 V and T_{opr} = 25 °C, unless otherwise specified.
2. This enables the setting errors of bit rates such as 9600 bps and 38400 bps to be 0% when the serial interface is used in UART mode.

Table 5.11 Low-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
fOCO-S	Low-speed on-chip oscillator frequency		60	125	250	kHz
—	Oscillation stability time	V_{CC} = 5.0 V, T_{opr} = 25 °C	—	30	TBD	µs
—	Self power consumption at oscillation	V_{CC} = 5.0 V, T_{opr} = 25 °C	—	2	—	µA

Note:
1. V_{CC} = 1.8 to 5.5 V and T_{opr} = –20 to 85 °C (N version), unless otherwise specified.

Table 5.12 Power Supply Circuit Timing Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
$t_{d(P-R)}$	Time for internal power supply stabilization during power-on (2)		—	—	2,000	µs

Notes:
1. The measurement condition is V_{CC} = 1.8 to 5.5 V and T_{opr} = 25 °C.
2. Waiting time until the internal power supply generation circuit stabilizes during power-on.

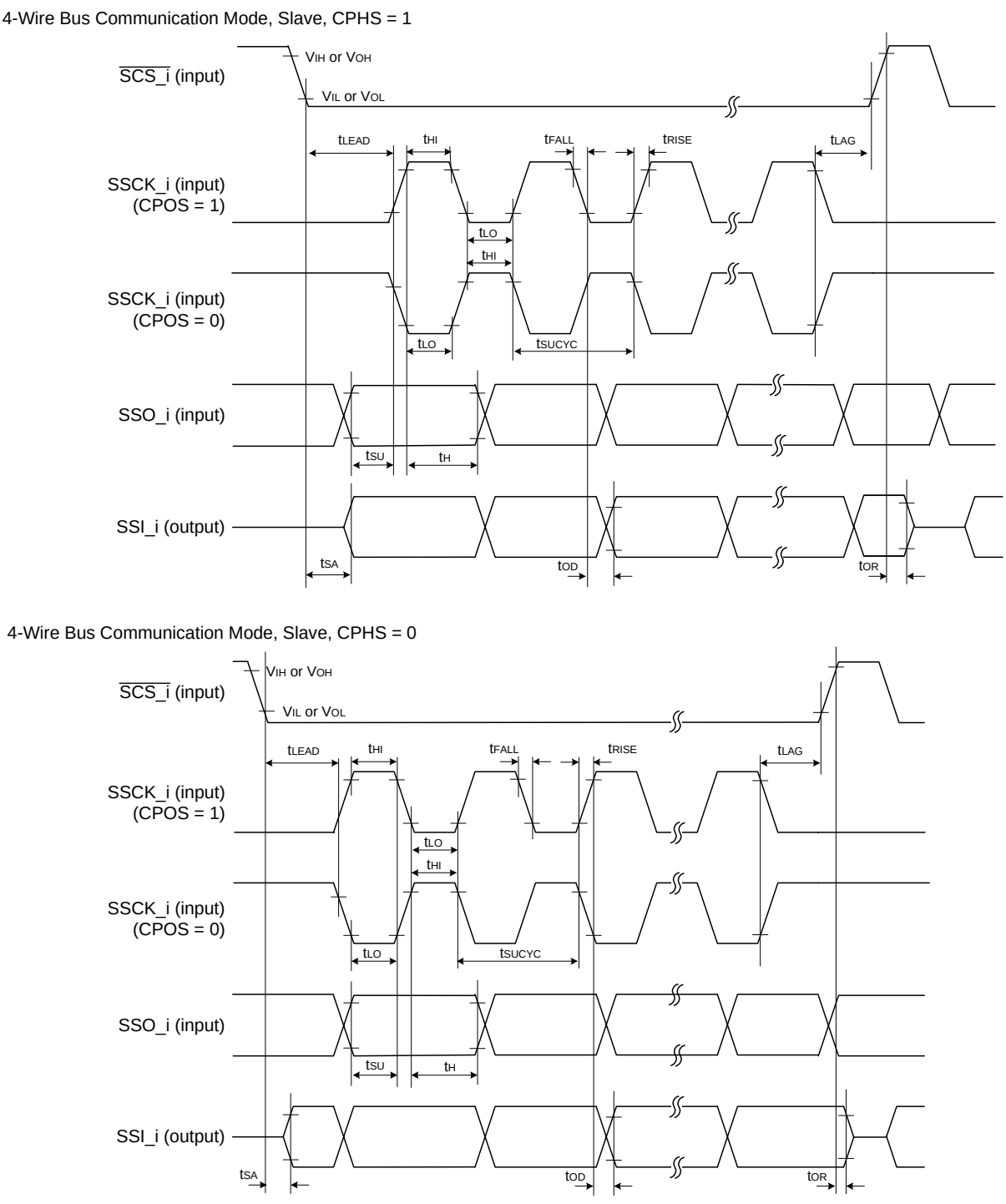


Figure 5.5 I/O Timing of Synchronous Serial Communication Unit (SSU) (Slave)

Table 5.21 Electrical Characteristics (3) [2.7 V ≤ Vcc < 4.2 V]

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output “H” voltage	Other than XOUT	Drive capacity High	V_{CC} = 3 V I_{OH} = –5 mA Maximum number of I/Os = 4	V_{CC} – 0.7	—	V_{CC}	V
			Drive capacity Low	V_{CC} = 3 V I_{OH} = –1 mA Maximum number of I/Os = 16	V_{CC} – 0.7	—	V_{CC}	V
		XOUT		I_{OH} = –200 µA	1.0	—	V_{CC}	V
V_{OL}	Output “L” voltage	Other than XOUT	Drive capacity High	V_{CC} = 3 V I_{OL} = 5 mA Maximum number of I/Os = 4	—	—	0.7	V
			Drive capacity Low	V_{CC} = 3 V I_{OL} = 1 mA Maximum number of I/Os = 16	—	—	0.7	V
		XOUT		I_{OL} = 200 µA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$, $\overline{INT1}$, $\overline{INT2}$, $\overline{INT3}$, $\overline{INT4}$, $\overline{KI0}$, $\overline{KI1}$, $\overline{KI2}$, $\overline{KI3}$, TRAIO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, $\overline{TRCTRG}$, TRCCLK, $\overline{ADTRG}$, RXD0, RXD1, RXD2, $\overline{CLK0}$, CLK1, $\overline{CLK2}$, $\overline{CTS2}$, SSCK_i, $\overline{SCS\_i}$, SSI_i, SCL_i, SDA_i, SSO_i (i = 0 to 3)	V_{CC} = 3.0 V		0.1	0.4	—	V
		$\overline{RESET}$	V_{CC} = 3.0 V		0.1	0.5	—	V
I_{IH}	Input “H” current		V_I = 3 V, V_{CC} = 3.0 V		—	—	4.0	µA
I_{IL}	Input “L” current		V_I = 0 V, V_{CC} = 3.0 V		—	—	–4.0	µA
R_{PULLUP}	Pull-up resistance		V_I = 0 V, V_{CC} = 3.0 V		42	84	168	kΩ
R_{fXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN			—	8	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Note:
1. 2.7 V ≤ V_{CC} < 4.2 V, T_{opr} = –20 to 85 °C (N version), and f(XIN) = 10 MHz, unless otherwise specified.

Table 5.22 Electrical Characteristics (4) [2.7 V ≤ Vcc ≤ 3.3 V] (Topr = –20 to 85 °C (N version), unless otherwise specified.)

Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
Icc	Power supply current (Vcc = 2.7 to 3.3 V) Single-chip mode, output pins are open, other pins are Vss	High-speed clock mode	XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	—	3.5	10	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	—	1.5	7.5	mA
		High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz No division	—	7.0	15	mA
			XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	—	3.0	—	mA
			XIN clock off High-speed on-chip oscillator on fOCO-F = 10 MHz Low-speed on-chip oscillator on = 125 kHz No division	—	4.0	—	mA
			XIN clock off High-speed on-chip oscillator on fOCO-F = 10 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	—	1.5	—	mA
			XIN clock off High-speed on-chip oscillator on fOCO-F = 4 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-16, MSTIIC = MSTTRD = MSTTRC = 1	—	1	—	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR27 = 1, VCA20 = 0	—	90	390	µA
		Low-speed clock mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz No division FMR27 = 1, VCA20 = 0	—	80	400	µA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz No division Program operation on RAM Flash memory off, FMSTP = 1, VCA20 = 0	—	40	—	µA
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0, VCA20 = 1	—	15	90	µA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0, VCA20 = 1	—	4	80	µA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz (peripheral clock off) While a WAIT instruction is executed VCA27 = VCA26 = VCA25 = 0, VCA20 = 1	—	3.5	—	µA
		Stop mode	XIN clock off, Topr = 25 °C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	—	2.0	5.0	µA
			XIN clock off, Topr = 85 °C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	—	15	—	µA

Timing requirements (Unless Otherwise Specified: V_{CC} = 3 V, V_{SS} = 0 V, T_{opr} = 25 °C)

Table 5.23 External Clock Input (XOUT, XCIN)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XOUT)}$	XOUT input cycle time	50	—	ns
$t_{WH(XOUT)}$	XOUT input “H” width	24	—	ns
$t_{WL(XOUT)}$	XOUT input “L” width	24	—	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	—	µs
$t_{WH(XCIN)}$	XCIN input “H” width	7	—	µs
$t_{WL(XCIN)}$	XCIN input “L” width	7	—	µs

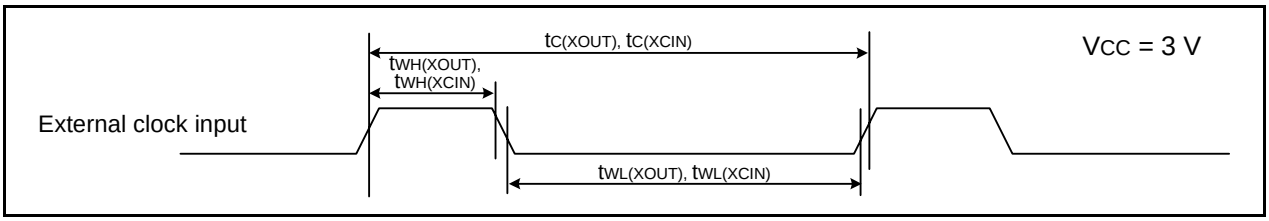


Figure 5.12 External Clock Input Timing Diagram when V_{CC} = 3 V

Table 5.24 TRAIO Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	300	—	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	120	—	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	120	—	ns

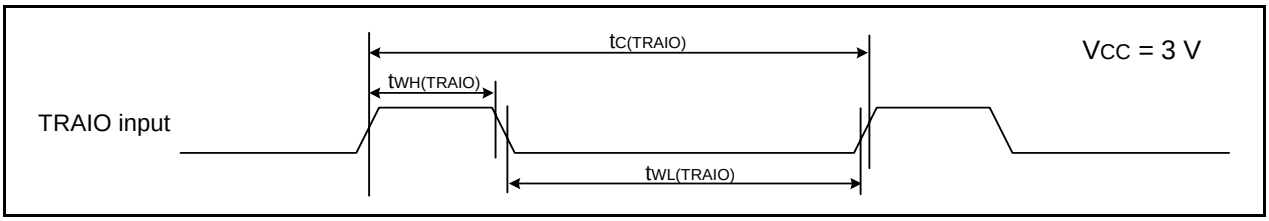


Figure 5.13 TRAIO Input Timing Diagram when V_{CC} = 3 V

Timing requirements (Unless Otherwise Specified: V_{CC} = 2.2 V, V_{SS} = 0 V, T_{opr} = 25 °C)

Table 5.29 External Clock Input (XOUT, XCIN)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XOUT)}$	XOUT input cycle time	200	—	ns
$t_{WH(XOUT)}$	XOUT input “H” width	90	—	ns
$t_{WL(XOUT)}$	XOUT input “L” width	90	—	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	—	µs
$t_{WH(XCIN)}$	XCIN input “H” width	7	—	µs
$t_{WL(XCIN)}$	XCIN input “L” width	7	—	µs

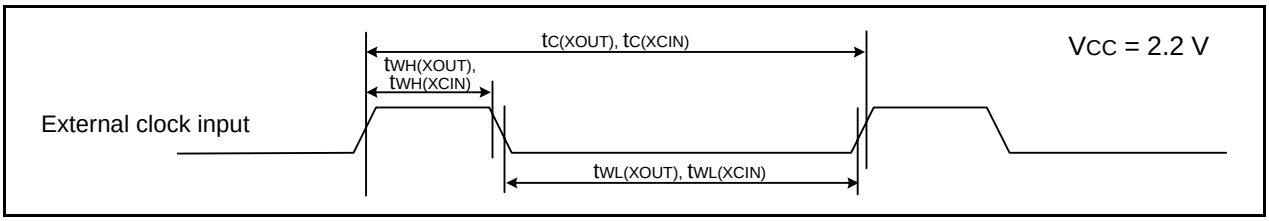


Figure 5.16 External Clock Input Timing Diagram when V_{CC} = 2.2 V

Table 5.30 TRAIO Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	500	—	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	200	—	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	200	—	ns

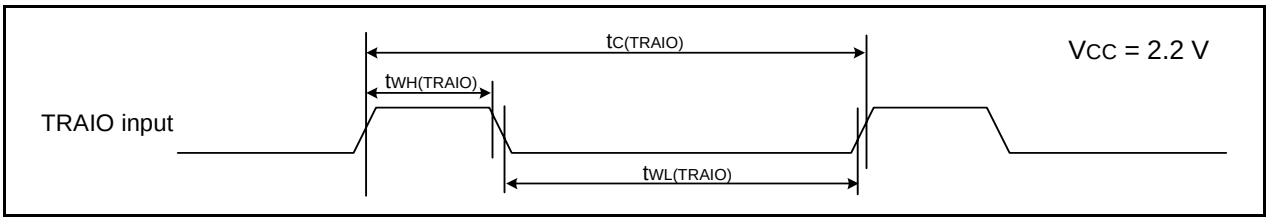


Figure 5.17 TRAIO Input Timing Diagram when V_{CC} = 2.2 V